

### CED4204-VB Datasheet

## N-Channel 40 V (D-S) MOSFET

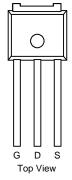
PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)		
40	0.0F3 at V <sub>GS</sub> = 10 V	55 <sup>d</sup>	F9.5		
40	0.0FI at $V_{GS} = 4.5 \text{ V}$	I 5 <sup>d</sup>	19.5		

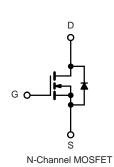
#### **FEATURES**

- · Halogen-free According to IEC 61249-2-21 Definition
- VBmos® Trench Cell
- 100 % R<sub>g</sub> and UIS Tested
- Compliant to RoHS Directive 2002/95/EC









#### **APPLICATIONS**

- · Power Supply
  - Secondary Synchronous Rectification
- DC/DC Converter

ABSOLUTE MAXIMUM RATINGS  Parameter	$_{\rm C}$ = 25 °C, unless our	Symbol	Limit	Unit	
	V <sub>DS</sub>	40	Unit		
Drain-Source Voltage				V	
Gate-Source Voltage		V <sub>GS</sub>	± 20		
Continuous Drain Current (T <sub>.I</sub> = 150 °C)	T <sub>C</sub> = 25 °C	I <sub>D</sub>	55 <sup>d</sup>	A	
Continuous Brain Current (1) = 100 C)	T <sub>C</sub> = 70 °C	טי	I 5 <sup>d</sup>		
Pulsed Drain Current		I <sub>DM</sub>	165		
Avalanche Current		I <sub>AS</sub>	H4		
Single Avalanche Energy <sup>a</sup>	L = 0.1 mH	E <sub>AS</sub>	Ϊ8	mJ	
	T <sub>C</sub> = 25 °C	Б	Í 5.5 <sup>b</sup>	W	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 25 °C <sup>c</sup>	$ P_D$	2.7		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS			
Parameter	Symbol	Limit	Unit
Junction-to-Ambient (PCB Mount) <sup>c</sup>	R <sub>thJA</sub>	ĺ4	°C/W
Junction-to-Case (Drain)	R <sub>thJC</sub>	2.Ï	C/VV

#### Notes:

- a. Duty cycle  $\leq$  1 %.
- b. See SOA curve for voltage derating.c. When mounted on 1" square PCB (FR-4 material).
- d. Package limited.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>DS</sub> = 0 V, I <sub>D</sub> = 250 μA	40		V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1		2.5	V
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 250	nA
		V <sub>DS</sub> = 40V, V <sub>GS</sub> = 0 V			1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 40V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50	μΑ
		V <sub>DS</sub> = 40V , V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150 °C			250	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	55			Α
Drain Source On State Registered	Б	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 22 A		0.0F3		Ω
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 20 A		0.0FI		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A		1€0		S
Dynamic <sup>b</sup>						
Input Capacitance	C <sub>iss</sub>			1100		pF
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 15 V, f = 1 MHz		460		
Reverse Transfer Capacitance	C <sub>rss</sub>			350		
Total Cata Charrel	Qg	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		H6		nC
Total Gate Charge <sup>c</sup>				25		
Gate-Source Charge <sup>c</sup>	$Q_{gs}$	$V_{DS}$ = 15 V, $V_{GS}$ = 4.5 V, $I_{D}$ = 20 A		Î		nC
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			ĺ.7		
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.4	2	4	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			8	16	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 15 V, $R_{L}$ = 1.5 $\Omega$		9	18	20
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		35	53	ns
Fall Time <sup>c</sup>	t <sub>f</sub>			9	18	1
Drain-Source Body Diode Ratings ar	nd Characteris	stics T <sub>C</sub> = 25 °C <sup>b</sup>				
Continuous Current	I <sub>S</sub>				55	^
Pulsed Current	I <sub>SM</sub>				165	Α
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 10 A, V <sub>GS</sub> = 0 V		0.75	1.5	V
Reverse Recovery Time	t <sub>rr</sub>			34	51	ns
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>	I <sub>F</sub> = 10 A, dI/dt = 100 A/μs		2	3	Α
Reverse Recovery Charge	Q <sub>rr</sub>			34	51	nC

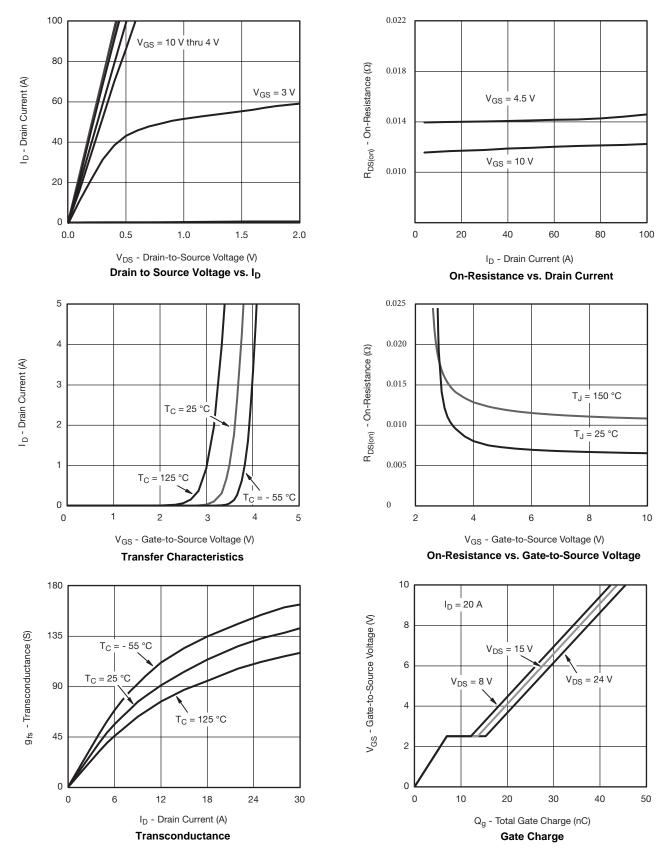
#### Notes:

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

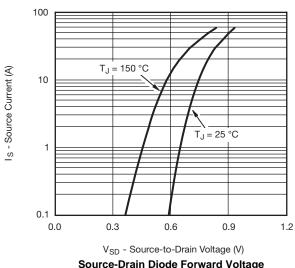


#### TYPICAL CHARACTERISTICS 25 C, unless otherwise noted

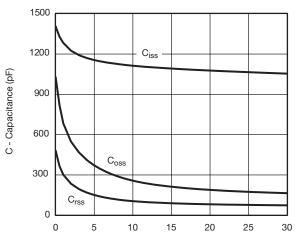




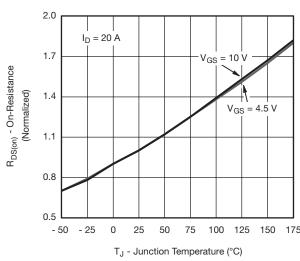
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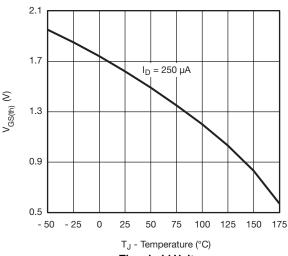
#### Source-Drain Diode Forward Voltage



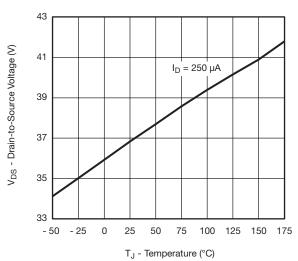
V<sub>DS</sub> - Drain-to-Source Voltage (V) Capacitance



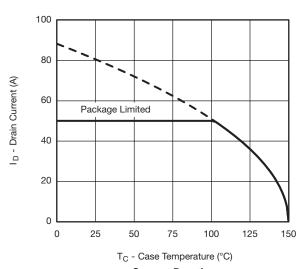
On-Resistance vs. Junction Temperature



Threshold Voltage



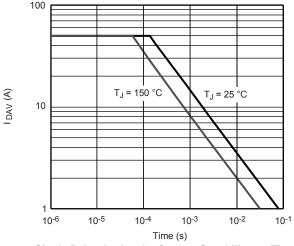
Drain Source Breakdown vs. Junction Temperature

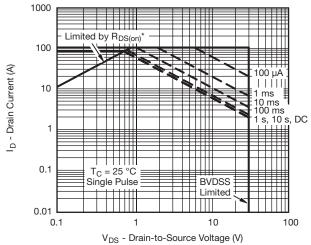


**Current Derating** 



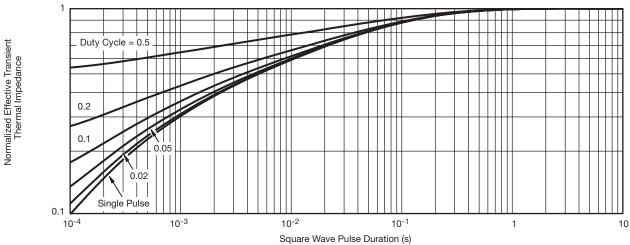
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Single Pulse Avalanche Current Capability vs. Time

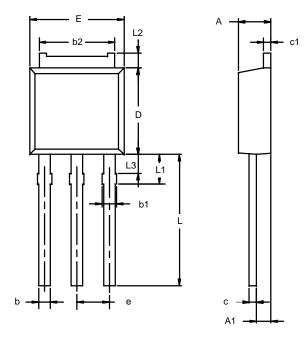
 $^{\star}$   $V_{GS}>$  minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Case



#### **TO-251AA**



Note: Dimension L3 is for reference only.

	MILLIM	ETERS	INCHES		
Dim	Min	Max	Min	Max	
Α	2.21	2.38	0.087	0.094	
<b>A</b> 1	0.89	1.14	0.035	0.045	
b	0.71	0.89	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.43	0.206	0.214	
С	0.46	0.58	0.018	0.023	
с1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
Е	6.48	6.73	0.255	0.265	
е	2.28 BSC		0.090 BSC		
L	3.89	9.53	0.153	0.375	
L1	1.91	2.28	0.075	0.090	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.045	0.060	
ECN: S-0	3946—Rev. E	, 09-Jul-01			

DWG: 5346



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